

# **FJH1100**

## **Information Only Data Sheet**

### FINAL REVERSE CURRENT & FORWARD VOLTAGE LIMITS MIGHT BE INCREASED SLIGHTLY

#### **General Description:**

An Ultra Low Leakage Diode in the DO-35 package. The forward voltage is typically greater than 0.5 volts at 1.0 micro-ampere.

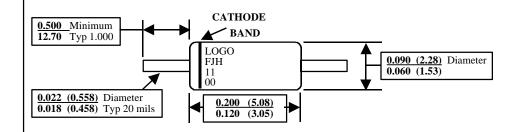
This product is light sensitive, any damage to the body coating will affect the reverse leakage when exposed to light

## **Ultra Low Leakage Diode**

Absolute Maximum Ratings\* TA = 25°C unless otherwise noted

Sym	Parameter	Value	Units
T <sub>stg</sub>	Storage Temperature	-55 to +200	°С
T <sub>J</sub>	Operating Junction Temperature	175	οС
P <sub>D</sub>	Total Power Dissipation at T <sub>A</sub> = 25°C	250	mW
	Linear Derating Factor from T <sub>A</sub> = 25 <sup>o</sup> C	1.67	mW/ <sup>O</sup> C
R <sub>OJA</sub>	Thermal Resistance Junction-to-Ambient	300	°C/W
W <sub>iv</sub>	Working Inverse Voltage	15	V
I <sub>F</sub>	DC Forward Current (IF)	150	mA

<sup>\*</sup>These ratings are limiting values above which the serviceability of any semiconductor device may be impaired



Typical Forward Voltages			
1.0 uA 530 mV			
10 uA 605 mV			
100 uA 685 mV			
1.0 mA 780 mV			
10 mA 895 mV			
50 mA 995 mV			
100 mA 1.07 V			

### **Electrical Characteristics**

TA = 25°C unless otherwise noted

SYM	CHARACTERISTICS	MIN	MAX	UNITS	TEST CONDITIONS
B <sub>V</sub>	Breakdown Voltage	30		V	$I_R = 5.0 \text{ uA}$
I <sub>R</sub>	Reverse Leakage		3.0 10	pA pA	$V_{R} = 5.0 V$ $V_{R} = 15 V$
V <sub>F</sub>	Forward Voltage		1.05	V	$I_F = 50 \text{ mA}$
$C_T$	Diode Capacitance		2.0	pF	$V_R = 0 V, f = 1.0 MHz$

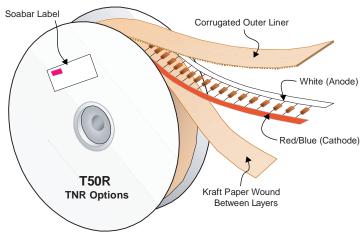
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## **DO-35 Tape and Reel Data**



DO-35 Packaging

Configuration: Figure 1.0



## DO-35 Packaging

**Information Table:** Figure 2.0

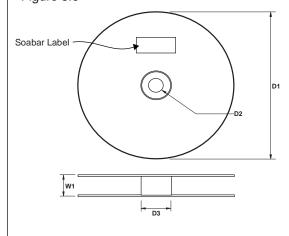
DO-35 Packaging Information					
Packaging Option	T50R	T50A	Standard (no flow code)		
Packaging type	TNR	Ammo	Bag		
Qty per Reel/Tube/Bag	10,000	5,000	500		
Reel Size (inch diameter)	13	-	-		
Inside Tape Spacing (mm)	52	52	-		
Int Box Dimension (mm)	254x79x794	406x267x184	279x133x108		
Max qty per Box	30,000	50,000	5,000		
Weight per unit (gm)	0.137	0.137	0.137		
Weight per Reel/Ammo (kg)	2.23	0.800	-		
Note/Comments			Bulk		

#### Soabar Label sample

FAIR	CHILD		
SEMICO	NDUCTOR.	P.O. No.	
TYPE	IN5225A	MARK	BLK-BRN
REV	A2	PART No.	
PKG		EC No.	
QTY	10,000	M.O. No.	OX5046F035
Q.C.		DATE	D9903
MFD. UNI	DER US PAT 3.025.589	& OTHER US PATS &	APPLICATIONS

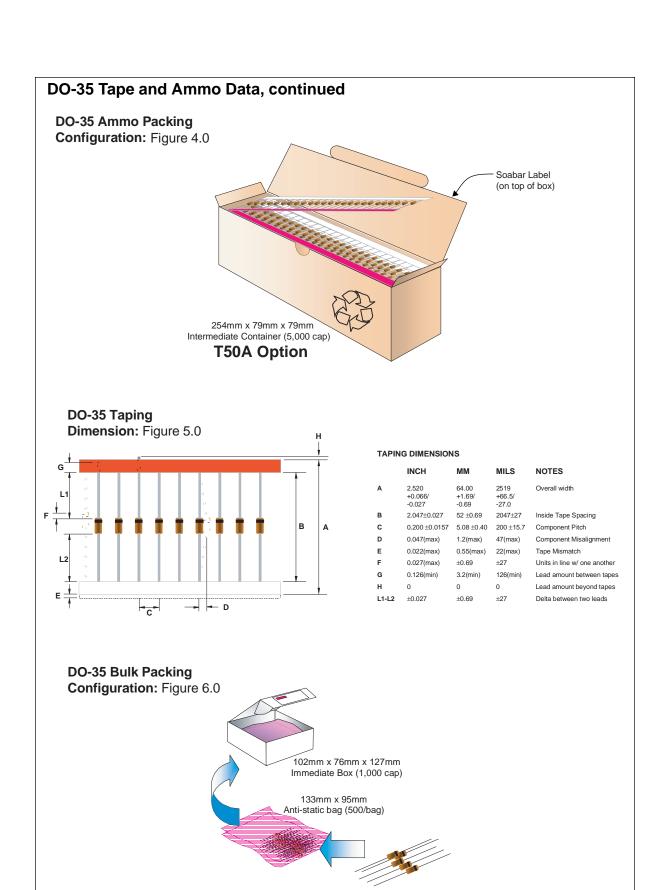
### **DO-35 Reel Dimensions:**

Figure 3.0



REEL DIMENSIONS				
ITEM DESCRIPTION	SYMBOL	MINIMUM	MAXIMUM	
Reel Diameter	D1	10.375	10.625	
Arbor Hole Diameter (Standard)	D2	1.245	1.255	
Core Diameter	D3	3.190	3.310	
Flange to Flange Inner Width	W1		3.400	
Note: All Dimensions are in inches				

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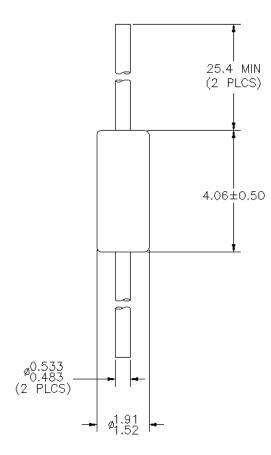


## **DO-35 Package Dimensions**



# DO-35 (FS PKG Code D2)







Scale 1:1 on letter size paper
Dimensions shown below are in millimeters
Part Weight per unit (gram): 0.137

NOTES: UNLESS OTHERWISE SPECIFIED

- A) THIS PACKAGE CONFORMS TO JEDEC D0-204, VAR. AH. ISSUE B. DATED JANUARY 20, 1976.
- B) HERMITICALLY SEALED GLASS PACKAGE

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EcoSPARK™	ISOPLANAR™	QS™	TinyLogic™
E <sup>2</sup> CMOS <sup>TM</sup>	LittleFET™	QT Optoelectronics™	TruTranslation™
EnSigna™	MicroFET™	Quiet Series™	UHC™
FACT™	MICROWIRE™	SILENT SWITCHER®	UltraFET ®
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